MSKSEMI 美森科













ESD

3

SS

MOV

GDT

PIFD

MSLM324DT

Product specification





GENERAL DESCRIPTION

The MSLM324DT consist of four independent, high g ain and internally frequency compensated operational amplifiers. They are specifically designed to operate fr om a single power supply. Operation from split power supplies is also possible and the low power supply c urrent drain is independent of the magnitude of the p ower supply voltage. Typical applications include trans ducer amplifiers, DC gain blocks and most convention al operational amplifier circuits.

The MSLM324DT is available in SOP-14 packages.

FEATURES

- Internally Frequency Compensated for Unity Gain
- Large Voltage Gain: 100dB (Typical)
- Low Input Bias Current: 20nA (Typical)
- Low Input Offset Voltage: 2mV (Typical)
- Low Supply Current: 0.5mA (Typical)
- Wide Power Supply Voltage Range:

Single Supply: 3V to 36V

Dual Supplies: ±1.5V to ±18V

- Input Common Mode Voltage Range Includes Ground
- Large Output Voltage Swing: 0V to Vcc -1.5V
- Power Drain Suitable for Battery Operation
- Lead-Free Packages: SOP-14

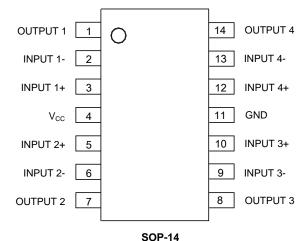
Applications

- Battery Charger
- Cordless Telephone
- Switching Power Supply

Reference News

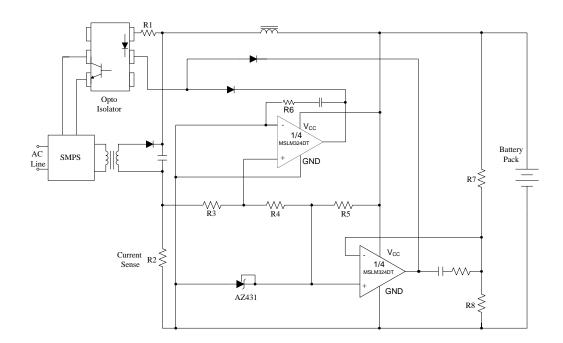
Type No	SOP-14	MARKING		
MSLM324DT	MELSENI E	MSKSEMI LM324DT MS**		

Pin Assignments

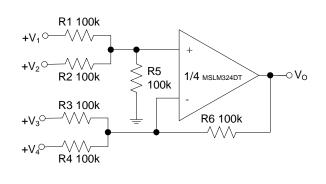


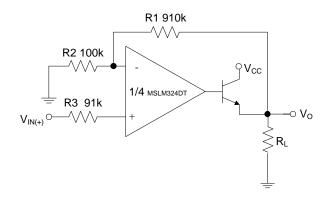


Typical Applications Circuit



Battery Charger



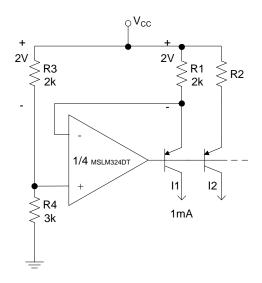


DC Summing Amplifier

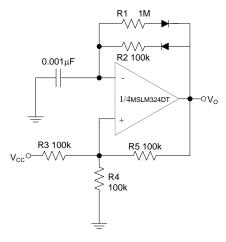
Power Amplifier



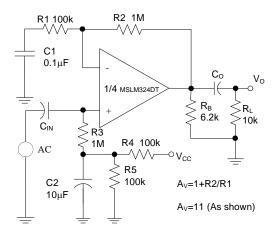
Typical Applications Circuit (continued)



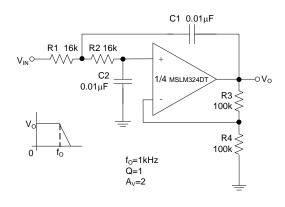
Fixed Current Sources



Pulse Generator



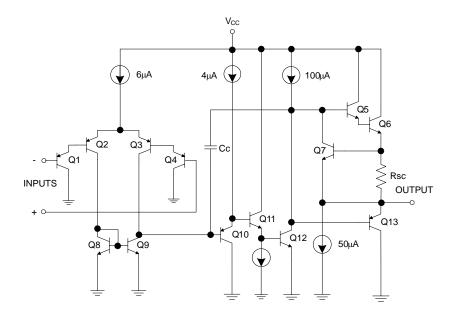
AC Coupled Non-Inverting Amplifier



DC Coupled Low-Pass RC Active Filter



Functional Block Diagram



Absolute Maximum Ratings (Note 4)

Symbol	Parameter	Rating	Unit
Vcc	Supply Voltage	40	V
VID	Differential Input Voltage	40	V
Vin	Input Voltage	-0.3 to 40	V
PD	Total Power Dissipation (T _A = +25°C)	800	mW
TJ	Operating Junction Temperature	+150	°C
Тѕтс	Storage Temperature Range	-65 to +150	°C
T _{LEAD} Lead Temperature (Soldering, 10 Seconds)		+260	°C

Note 4: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
Vcc	Supply Voltage	3	36	V
TA	T _A Ambient Operating Temperature Range		+85	°C



Electrical Characteristics (Limits in standard typeface are for TA = +25°C, **bold** typeface applies over TA = -40°C to +85°C (Note 5), V_{CC} = 5V, GND = 0V, unless otherwise specified.)

Symbol	Pai	rameter	Conditions		Min	Тур	Max	Unit
Vio Input Offset Voltage		Vo = 1.4V, Rs = 0Ω, Vcc = 5V to 30V		_	2	5	mV	
				_	_	7		
ΔV10/ΔΤ	Average Temperature Coefficient of Input Offset Voltage		T _A = -40 to +85°C		_	7	_	μV/°C
					_	5	30	
lio	Input Offset Current		lin+ - lin-, Vcm = 0V		_	_	100	nA
	Input Bias Current		last or last Your OV		_	20	100	^
IBIAS	Input bias Current		lin+ or l _{in} -, Vcm = 0V		_	_	200	nA
VIR	Input Common Mode Voltage Range (Note 6)		Vcc = 30V		0	_	Vcc- 1.5	V
	Supply Current		T _A = -40 to +85°C,	Vcc = 30V	_	1.0	3	mA
lcc	Supply Current		R _L = ∞	Vcc = 5V	_	0.7	1.2	
Gv	Large Signal Voltage G	Gain Vcc = 15V, F	Voc = 15V B > 2k0	> 01:0 1/- 41/4- 441/	85	100	_	dB
G۷	Large Signal Voltage C		Vcc = 15V, RL≥ 2kΩ, Vo = 1V to 11V		80	_	_	Ф
CMRR	Common Mode Reject	DC Vov 0 to 0/ 4 5 V	60	70	_	- dB		
CIVITAIX	CMRR Common Mode Rejection Ratio		DC, VcM = 0 to (Vcc-1.5)V		60		_	_
PSRR Power Supply Rejection Ratio		n Patio	Vcc = 5 to 30V		70	100	_	dB
FOINIX	Power Supply Rejection Ratio				60	_	_	
CS	Channel Separation		f = 1kHz to 20kHz		_	-120	_	dB
1		Source	V IN+ = 1V, VIN- = 0V, VCC = 15V, Vo = 2V		20	40	_	- mA
Isource					20	_	_	
	Output Current	t Sink	V _{IN+} = 0V, V _{IN-} = 1V, V _{CC} = 15V, V _O = 2V V _{IN+} = 0V, V _{IN-} = 1V, V _{CC} = 15V, V _O = 0.2V		10	15	_	- mA
Isink					5	_	_	
					12	50	_	μΑ
Isc	Output Short Circuit Current to Ground		Vcc = 15V		_	40	60	mA
Voн Output Voltage Swing			Vcc = 30V, RL = 2kΩ		26	_	_	V
					26	_	_	
	Voc = 20V Pt = 40k0		27	28	_	. v		
Output Voltage Swing		Vcc = 30V, RL = 10kΩ		27	_		_	
Voi			$Vcc = 5V$, $RL = 10k\Omega$	_	5	20	mV	
VoL			V CC - 3V, RL - 10K12		_	_	30	1110
θ_{JC}	Thermal Resistance (Junction to Case)		SOP-14			18		°C/W
θЈΑ	Thermal Resistance (J	Thermal Resistance (Junction to Ambient)			_	91	_	°C/W

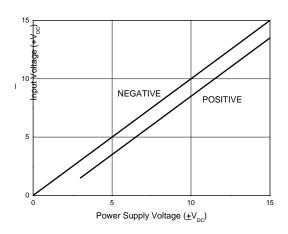
Notes: 1. Limits over the full temperature are guaranteed by design, but not tested in production.

2. The input common-mode voltage of either input signal voltage should not be allowed to go negatively by more than 0.3V (at +25°C). The upper end of the common-mode voltage range is VCC -1.5V (at +25°C), but either or both inputs can go to +36V without damages, independent of the magnitude of the VCC.

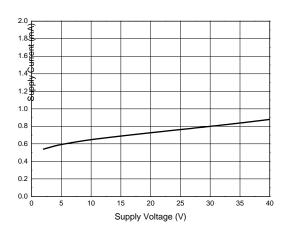


Performance Characteristics

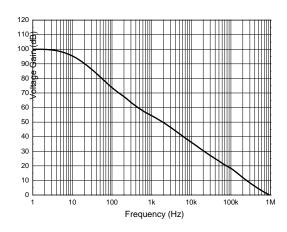
Input Voltage Range



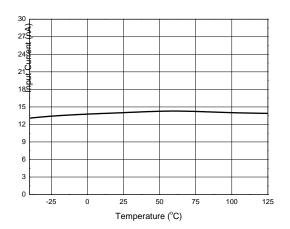
Supply Current



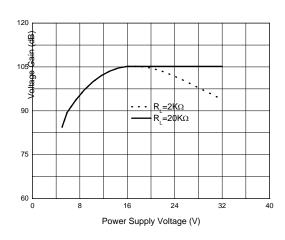
Open Loop Frequency Response



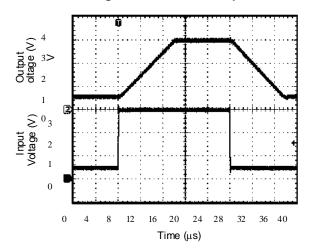
Input Current



Voltage Gain



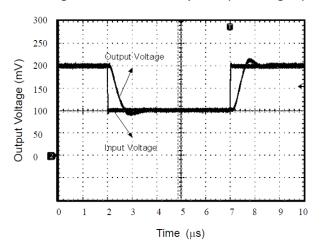
Voltage Follower Pulse Response



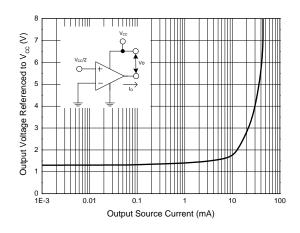


Performance Characteristics (continued)

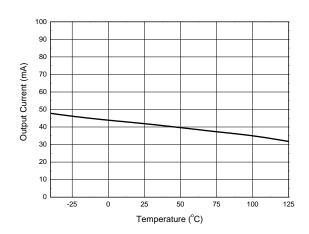
Voltage Follower Pulse Response (Small Signal)



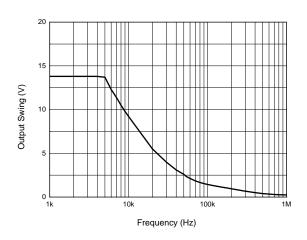
Output Characteristics: Current Sourcing



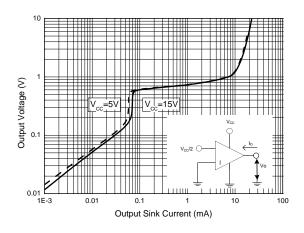
Current Limiting



Large Signal Frequency Response



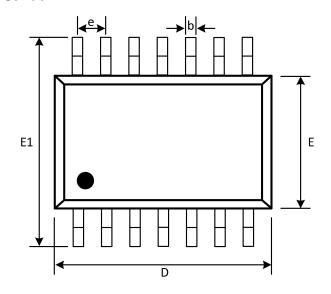
Output Characteristics: Current Sinking

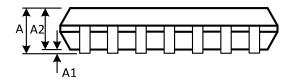


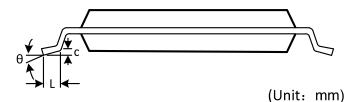


PACKAGE DESCRIPTION

SOP-14







Symbol Min Max Α 1.350 1.750 Α1 0.100 0.250 A2 1.350 1.550 b 0.310 0.510 0.100 0.250 С D 8.450 8.850 1.270(BSC) е Ε 5.800 6.200 E1 4.000 3.800 L 0.400 1.270 0° 8° θ

REEL SPECIFICATION

P/N	PKG	QTY
MSLM324DT)	SOP-14	2500



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